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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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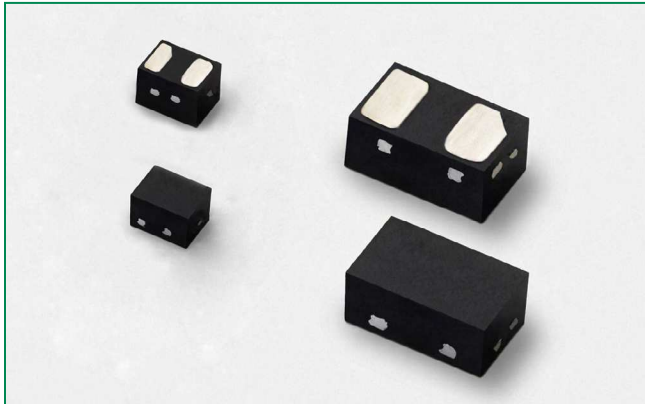
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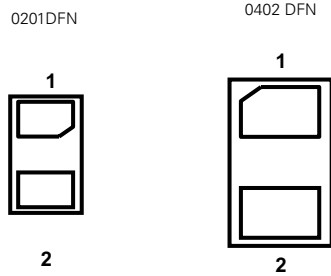
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**SESD Series Ultra Low Capacitance Discrete TVS**  **AUTOMOTIVE GRADE**  **RoHS**  **Pb**  **GREEN**  **ELV**

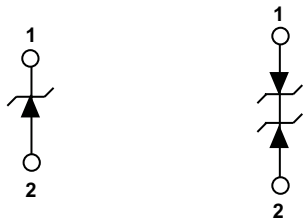


**Pinout**



Bottom View

**Functional Block Diagram**



Unidirectional

Bidirectional

**Description**

The SESD Series Ultra Low Capacitance Discrete TVS provides unidirectional and bidirectional ESD protection for the world's most challenging high speed serial interfaces. Ultra low capacitance permits excellent signal integrity on the most challenging consumer electronics interfaces, such as USB 3.1, HDMI 2.0, DisplayPort, and V-by-One®. Providing in excess of 20kV contact ESD protection (IEC61000-4-2) while maintaining extremely low leakage and dynamic resistance, offered in the industry's most popular footprints (0402 and 0201), the SESD series sets higher standards for signal integrity and usability.

**Features**

- 0.13pF MAX bidirectional
- 0.25pF MAX unidirectional
- ESD, IEC61000-4-2, ±20kV contact, ±20kV air
- Low clamping voltage of 10V @ I<sub>pp</sub>=2A (Bidirectional) (t<sub>p</sub>=8/20µs)
- Low profile 0201 and 0402 DFN packages
- Facilitates excellent signal integrity
- AEC-Q101 qualified
- ELV Compliant

**Applications**

- Ultra-high speed data lines
- USB 3.1, 3.0, 2.0
- HDMI 2.0, 1.4a, 1.3
- DisplayPort™
- Thunderbolt (Light Peak)
- V-by-One®
- LVDS interfaces
- Consumer, mobile and portable electronics
- Tablet PC and external storage with high speed interfaces
- Applications requiring high ESD performance in small packages

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	2.0	A
$T_{OP}$	Operating Temperature	-55 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Thermal Information

Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

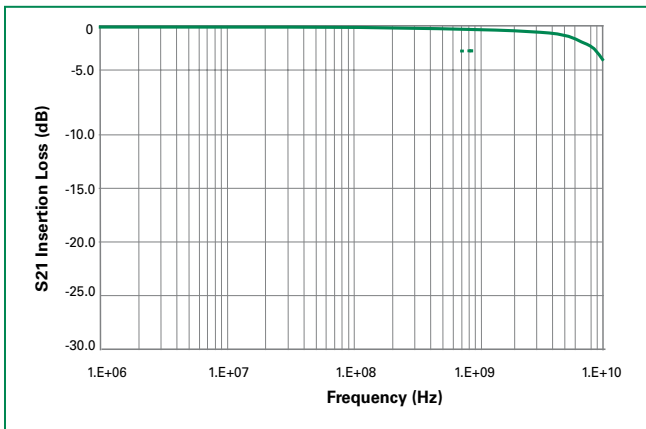
### Unidirectional Electrical Characteristics - ( $T_{OP}=25^\circ C$ )

Parameter	Test Conditions	Min	Typ	Max	Units
Input Capacitance	@ $V_R = 0V$ , $f = 3GHz$		0.20	0.25	pF
Breakdown Voltage	$V_{BR}$ @ $I_T=1mA$		9.00		V
Reverse Working Voltage				7.0	V
Reverse Leakage Current	$I_L$ @ $V_{RWM}=5.0V$		25	50	nA
Clamping Voltage	$V_{CL}$ @ $I_{PP}=2.0A$		9.20		V
ESD Withstand Voltage	IEC61000-4-2 (Contact)	±20			kV
	IEC61000-4-2 (Air)	±20			

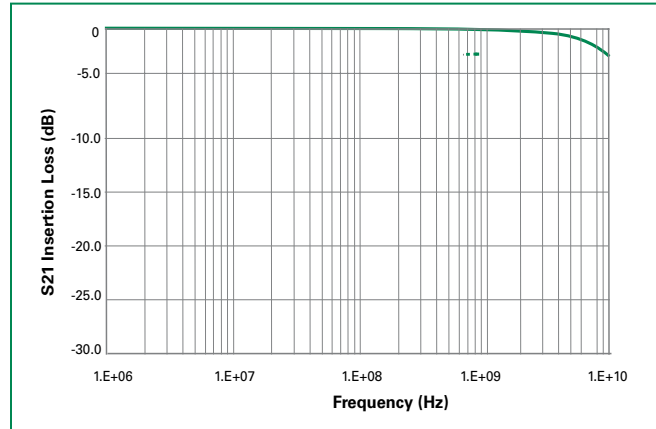
### Bidirectional Electrical Characteristics - ( $T_{OP}=25^\circ C$ )

Parameter	Test Conditions	Min	Typ	Max	Units
Input Capacitance	@ $V_R = 0V$ , $f = 3GHz$		0.10	0.13	pF
Breakdown Voltage	$V_{BR}$ @ $I_T=1mA$		9.80		V
Reverse Working Voltage		-7.0		7.0	V
Reverse Leakage Current	$I_L$ @ $V_{RWM}=5.0V$		25	50	nA
Clamping Voltage	$V_{CL}$ @ $I_{PP}=2.0A$		10.0		V
ESD Withstand Voltage	IEC61000-4-2 (Contact)	±20			kV
	IEC61000-4-2 (Air)	±20			

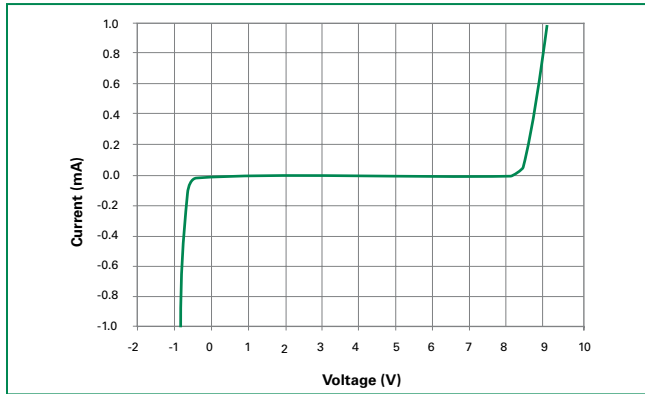
### Insertion Loss Diagram - Unidirectional



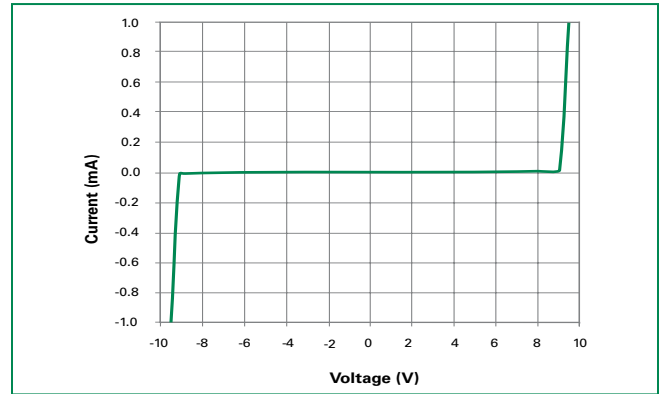
### Insertion Loss Diagram - Bidirectional



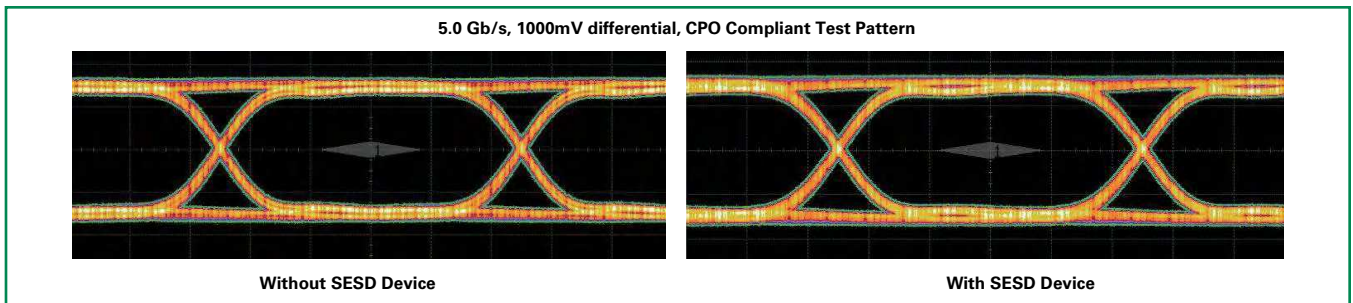
**Device IV Curve - Unidirectional**



**Device IV Curve - Bidirectional**

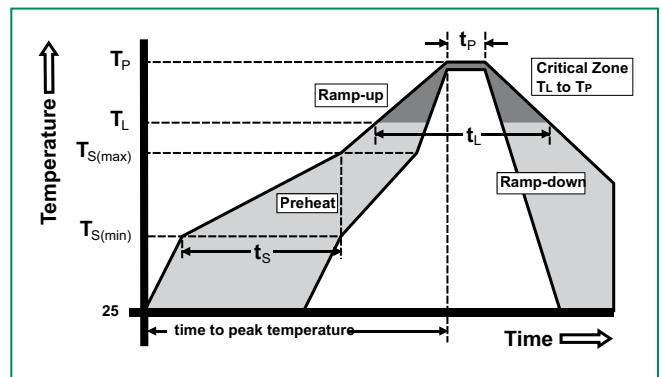


**USB3.0 Eye Diagram**



**Soldering Parameters**

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes Max.
Do not exceed		260°C

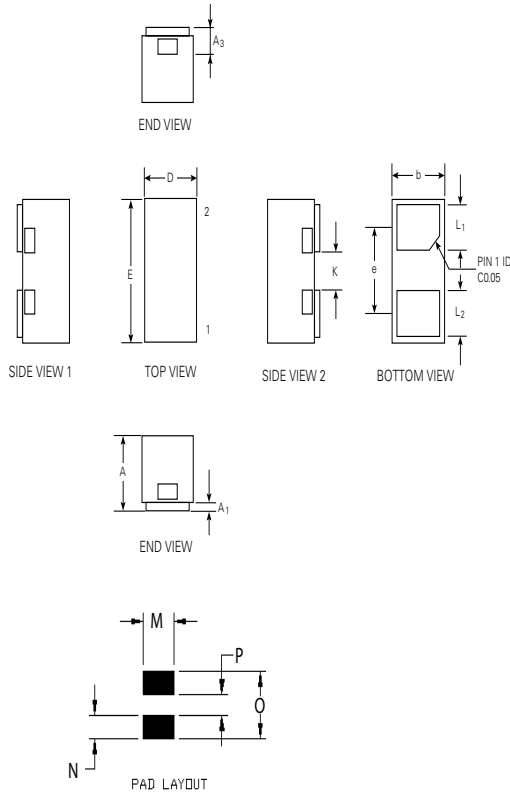


**Product Characteristics of 0402 DFN Package**

<b>Lead Plating</b>	Pre-Plated Frame
<b>Lead Material</b>	Copper Alloy
<b>Lead Coplanarity</b>	0.0004 inches (0.102mm)
<b>Substrate material</b>	Silicon
<b>Body Material</b>	Molded Epoxy
<b>Flammability</b>	UL 94 V-0

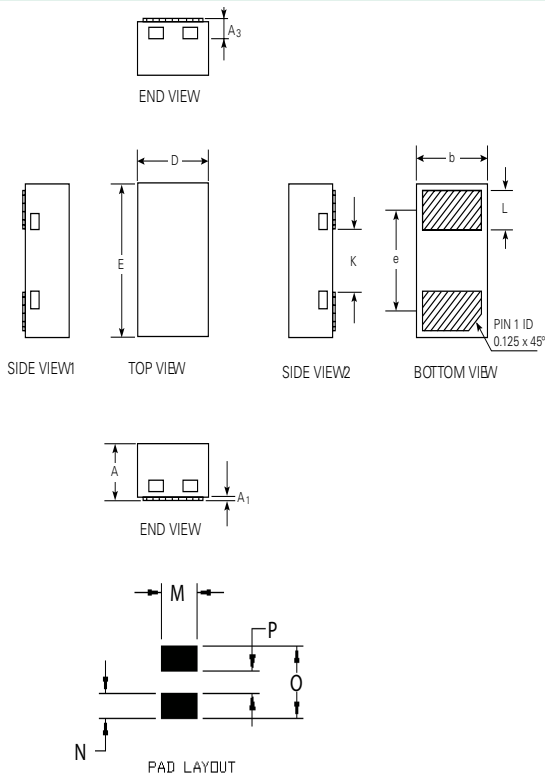
- Notes :
1. All dimensions are in millimeters
  2. Dimensions include solder plating.
  3. Dimensions are exclusive of mold flash & metal burr.
  4. Bld is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
  5. Package surface matte finish VDI 11-13.

**Package Dimensions — 0201 DFN**



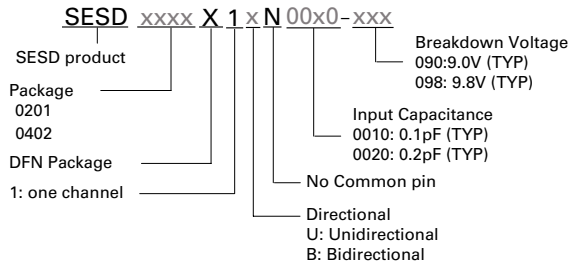
Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.28	0.30	0.32	0.011	0.012	0.013
A1	0	-	0.05	0	-	0.002
A3	0.102 ref.			0.004 ref.		
D	0.25	0.30	0.35	0.010	0.012	0.014
E	0.55	0.60	0.65	0.022	0.024	0.026
K	0.11	0.17	0.22	0.004	0.007	0.009
b	0.20	0.25	0.30	0.008	0.010	0.012
L1	0.13	0.18	0.23	0.005	0.008	0.009
L2	0.14	0.19	0.24	0.006	0.007	0.009
e	0.356 BSC			0.014 BSC		
M		0.32			0.013	
N		0.24			0.009	
O		0.62			0.024	
P		0.14			0.006	

**Package Dimensions — 0402 DFN**

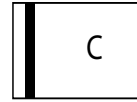


Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	0.33	0.38	0.43	0.013	0.015	0.017
A1	0	-	0.05	0	-	0.002
A3	0.13 ref.			0.005 ref.		
D	0.55	0.60	0.65	0.022	0.024	0.026
E	0.95	1.00	1.05	0.037	0.039	0.041
K	0.35	0.40	0.45	0.014	0.016	0.018
b	0.45	0.50	0.55	0.018	0.020	0.022
L	0.20	0.25	0.30	0.008	0.010	0.012
e	0.65 BSC			0.026 BSC		
M		0.60			0.024	
N		0.35			0.014	
O		1.00			0.039	
P		0.30			0.012	

### Part Numbering System



### Part Marking System



Unidirectional

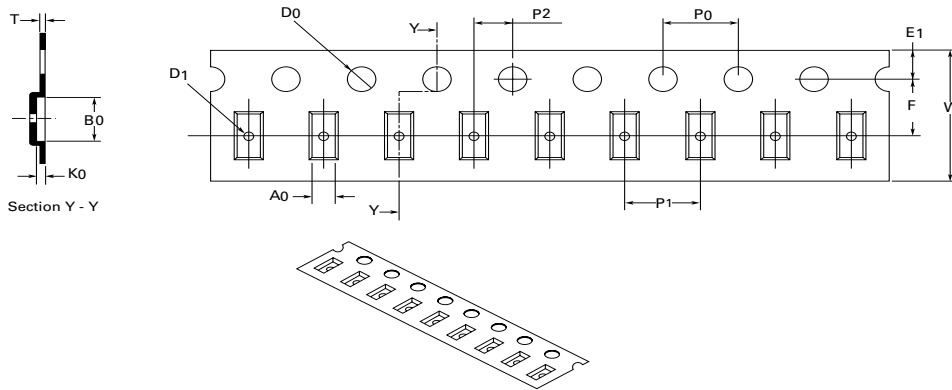


Bidirectional

### Ordering Information

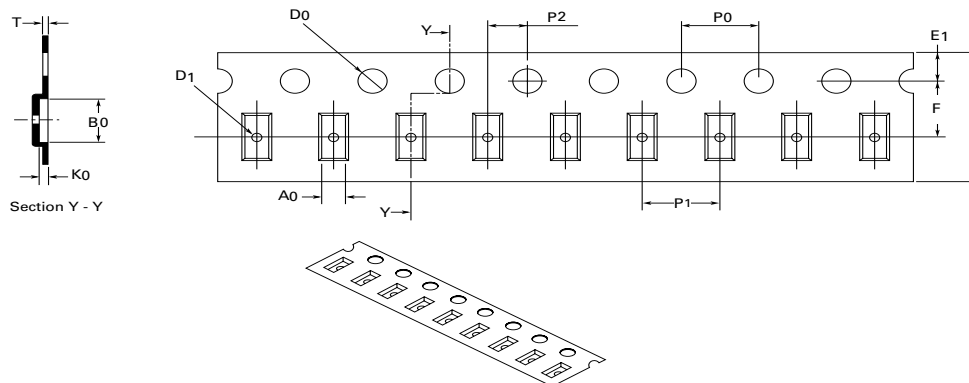
Part Number	Package	Marking	Ordering Part Number	Components/Reel Quantity
SESD0201X1UN-0020-090	0201 DFN	C	RF2192-000	15000
SESD0201X1BN-0010-098	0201 DFN	C	RF2193-000	15000
SESD0402X1UN-0020-090	0402 DFN	C	RF2943-000	10000
SESD0402X1BN-0010-098	0402 DFN	C	RF2945-000	10000

### Embossed Carrier Tape & Reel Specification – 0201 DFN



Symbol	Millimeters
<b>A0</b>	0.36+/-0.03
<b>B0</b>	0.66+/-0.03
<b>D0</b>	∅ 1.50 + 0.10/-0
<b>D1</b>	∅ 0.20 +/- 0.05
<b>E1</b>	1.75+/-0.10
<b>F</b>	3.50+/-0.05
<b>K0</b>	0.33+/-0.03
<b>P0</b>	4.00+/-0.10
<b>P1</b>	2.00+/-0.10
<b>P2</b>	2.00+/-0.05
<b>W</b>	8.00 +/-0.10
<b>T</b>	0.23+/-0.02

### Embossed Carrier Tape & Reel Specification – 0402 DFN



Symbol	Millimeters
<b>A0</b>	0.70+/-0.05
<b>B0</b>	1.15+/-0.05
<b>D0</b>	∅ 1.55 + 0.05
<b>D1</b>	∅ 0.40 +/- 0.05
<b>E1</b>	1.75+/-0.10
<b>F</b>	3.50+/-0.05
<b>K0</b>	0.47+/-0.05
<b>P0</b>	4.00+/-0.10
<b>P1</b>	2.00+/-0.10
<b>P2</b>	2.00+/-0.05
<b>W</b>	8.00 +/-0.10
<b>T</b>	0.20+/-0.05